

Final datasheet

EconoDUAL™3 module with TRENCHSTOP™ IGBT7 and emitter controlled 7 diode and NTC / pre-applied thermal interface material

Features

- Electrical features
 - $V_{CES} = 1200\text{ V}$
 - $I_{C\text{ nom}} = 900\text{ A} / I_{CRM} = 1800\text{ A}$
 - Integrated temperature sensor
 - TRENCHSTOP™ IGBT7
 - $V_{CE,sat}$ with positive temperature coefficient
- Mechanical features
 - High power density
 - Isolated base plate
 - Pre-applied thermal interface material
 - PressFIT contact technology
 - Standard housing



Potential applications

- UPS systems
- Servo drives
- Motor drives
- Commercial agriculture vehicles
- High-power converters

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description

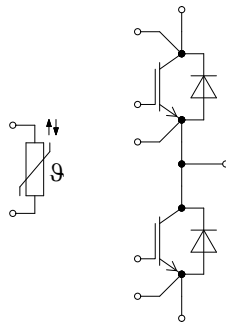




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1 Package

1 Package

Table 1 **Insulation coordination**

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50 \text{ Hz}$, $t = 1 \text{ min}$	3.4	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	$d_{Creep \text{ nom}}$	terminal to baseplate, nom.	> 15	mm
Creepage distance	$d_{Creep \text{ min}}$	terminal to baseplate, min.	14.7	mm
Creepage distance	$d_{Creep \text{ nom}}$	terminal to terminal, nom.	12.1	mm
Creepage distance	$d_{Creep \text{ min}}$	terminal to terminal, min.	11.5	mm
Clearance	$d_{Clear \text{ nom}}$	terminal to baseplate, nom.	> 12.5	mm
Clearance	$d_{Clear \text{ min}}$	terminal to baseplate, min.	12.5	mm
Clearance	$d_{Clear \text{ nom}}$	terminal to terminal, nom.	10.0	mm
Clearance	$d_{Clear \text{ min}}$	terminal to terminal, min.	9.6	mm
Comparative tracking index	CTI		> 200	
Relative thermal index (electrical)	RTI	housing	140	°C

Table 2 **Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Stray inductance module	L_{sCE}				20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_H = 25\text{ }^{\circ}\text{C}$, per switch			0.8		mΩ
Storage temperature	T_{stg}			-40		125	°C
Maximum baseplate operation temperature	T_{BPmax}					150	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3		6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	3		6	Nm
Weight	G				345		g

Note: Storage and shipment of modules with TIM => see AN2012-07

2 IGBT, Inverter

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		$T_{vj} = 25\text{ °C}$	1200	V
Implemented collector current	I_{CN}			900	A
Continuous DC collector current	I_{CDC}	$T_{vj\text{ max}} = 175\text{ °C}$	$T_H = 45\text{ °C}$	875	A
Maximum RMS module DC-terminal current	I_{tRMS}		$T_{\text{Terminal}} = 90\text{ °C}$, $T_C = 90\text{ °C}$	580	A
			$T_{\text{Terminal}} = 105\text{ °C}$, $T_C = 90\text{ °C}$	565	
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\text{ op}}$		1800	A
Gate-emitter peak voltage	V_{GES}			±20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\text{ sat}}$	$I_C = 900\text{ A}$, $V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$		1.50	1.80	V
			$T_{vj} = 125\text{ °C}$		1.65		
			$T_{vj} = 175\text{ °C}$		1.75		
Gate threshold voltage	V_{GETh}	$I_C = 18\text{ mA}$, $V_{CE} = V_{GE}$, $T_{vj} = 25\text{ °C}$		5.15	5.80	6.45	V
Gate charge	Q_G	$V_{GE} = \pm 15\text{ V}$, $V_{CC} = 600\text{ V}$			14.3		μC
Internal gate resistor	R_{Gint}	$T_{vj} = 25\text{ °C}$			0.5		Ω
Input capacitance	C_{ies}	$f = 100\text{ kHz}$, $T_{vj} = 25\text{ °C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$			122		nF
Reverse transfer capacitance	C_{res}	$f = 100\text{ kHz}$, $T_{vj} = 25\text{ °C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$			0.72		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200\text{ V}$, $V_{GE} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$			0.1	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$, $T_{vj} = 25\text{ °C}$				100	nA
Turn-on delay time (inductive load)	t_{don}	$I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 0.51\text{ Ω}$	$T_{vj} = 25\text{ °C}$		0.410		μs
			$T_{vj} = 125\text{ °C}$		0.460		
			$T_{vj} = 175\text{ °C}$		0.490		
Rise time (inductive load)	t_r	$I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 0.51\text{ Ω}$	$T_{vj} = 25\text{ °C}$		0.100		μs
			$T_{vj} = 125\text{ °C}$		0.110		
			$T_{vj} = 175\text{ °C}$		0.120		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-off delay time (inductive load)	t_{doff}	$I_C = 900 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $R_{\text{Goff}} = 0.51 \Omega$	$T_{vj} = 25 \text{ °C}$	0.550		μs
			$T_{vj} = 125 \text{ °C}$	0.630		
			$T_{vj} = 175 \text{ °C}$	0.690		
Fall time (inductive load)	t_f	$I_C = 900 \text{ A}$, $V_{CC} = 600 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$, $R_{\text{Goff}} = 0.51 \Omega$	$T_{vj} = 25 \text{ °C}$	0.110		μs
			$T_{vj} = 125 \text{ °C}$	0.230		
			$T_{vj} = 175 \text{ °C}$	0.330		
Turn-on energy loss per pulse	E_{on}	$I_C = 900 \text{ A}$, $V_{CC} = 600 \text{ V}$, $L_\sigma = 25 \text{ nH}$, $V_{GE} = \pm 15 \text{ V}$, $R_{\text{Gon}} = 0.51 \Omega$, $di/dt = 6200 \text{ A}/\mu\text{s}$ ($T_{vj} = 175 \text{ °C}$)	$T_{vj} = 25 \text{ °C}$	89		mJ
			$T_{vj} = 125 \text{ °C}$	138		
			$T_{vj} = 175 \text{ °C}$	170		
Turn-off energy loss per pulse	E_{off}	$I_C = 900 \text{ A}$, $V_{CC} = 600 \text{ V}$, $L_\sigma = 25 \text{ nH}$, $V_{GE} = \pm 15 \text{ V}$, $R_{\text{Goff}} = 0.51 \Omega$, $dv/dt = 3000 \text{ V}/\mu\text{s}$ ($T_{vj} = 175 \text{ °C}$)	$T_{vj} = 25 \text{ °C}$	89		mJ
			$T_{vj} = 125 \text{ °C}$	130		
			$T_{vj} = 175 \text{ °C}$	158		
SC data	I_{SC}	$V_{GE} \leq 15 \text{ V}$, $V_{CC} = 800 \text{ V}$, $V_{CE\text{max}} = V_{CES} - L_{sCE} \cdot di/dt$	$t_p \leq 8 \mu\text{s}$, $T_{vj} = 150 \text{ °C}$	3200		A
			$t_p \leq 6 \mu\text{s}$, $T_{vj} = 175 \text{ °C}$	3000		
Thermal resistance, junction to heat sink	R_{thJH}	per IGBT, Valid with IFX pre-applied Thermal Interface Material			0.0720	K/W
Temperature under switching conditions	$T_{vj\text{op}}$		-40		175	°C

Note: $T_{vj\text{op}} > 150 \text{ °C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

3 Diode, Inverter

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25 \text{ °C}$	1200	V
Continuous DC forward current	I_F		900	A
Repetitive peak forward current	I_{FRM}	$t_p = 1 \text{ ms}$	1800	A
I^2t - value	I^2t	$t_p = 10 \text{ ms}$, $V_R = 0 \text{ V}$	$T_{vj} = 125 \text{ °C}$	A^2s
			$T_{vj} = 175 \text{ °C}$	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F = 900 \text{ A}$, $V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	1.80	2.05	V
			$T_{vj} = 125 \text{ °C}$	1.70		
			$T_{vj} = 175 \text{ °C}$	1.65		
Peak reverse recovery current	I_{RM}	$V_{CC} = 600 \text{ V}$, $I_F = 900 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 6200 \text{ A}/\mu\text{s}$ ($T_{vj} = 175 \text{ °C}$)	$T_{vj} = 25 \text{ °C}$	389		A
			$T_{vj} = 125 \text{ °C}$	511		
			$T_{vj} = 175 \text{ °C}$	578		
Recovered charge	Q_r	$V_{CC} = 600 \text{ V}$, $I_F = 900 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 6200 \text{ A}/\mu\text{s}$ ($T_{vj} = 175 \text{ °C}$)	$T_{vj} = 25 \text{ °C}$	65		μC
			$T_{vj} = 125 \text{ °C}$	127		
			$T_{vj} = 175 \text{ °C}$	171		
Reverse recovery energy	E_{rec}	$V_{CC} = 600 \text{ V}$, $I_F = 900 \text{ A}$, $V_{GE} = -15 \text{ V}$, $-di_F/dt = 6200 \text{ A}/\mu\text{s}$ ($T_{vj} = 175 \text{ °C}$)	$T_{vj} = 25 \text{ °C}$	29		mJ
			$T_{vj} = 125 \text{ °C}$	52		
			$T_{vj} = 175 \text{ °C}$	68		
Thermal resistance, junction to heat sink	R_{thJH}	per diode, Valid with IFX pre-applied Thermal Interface Material			0.126	K/W
Temperature under switching conditions	$T_{vj \text{ op}}$		-40		175	°C

Note: $T_{vj \text{ op}} > 150 \text{ °C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

4 NTC-Thermistor

Table 7 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	$T_{NTC} = 25 \text{ °C}$		5		kΩ
Deviation of R_{100}	$\Delta R/R$	$T_{NTC} = 100 \text{ °C}$, $R_{100} = 493 \text{ Ω}$	-5		5	%
Power dissipation	P_{25}	$T_{NTC} = 25 \text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$		3433		K

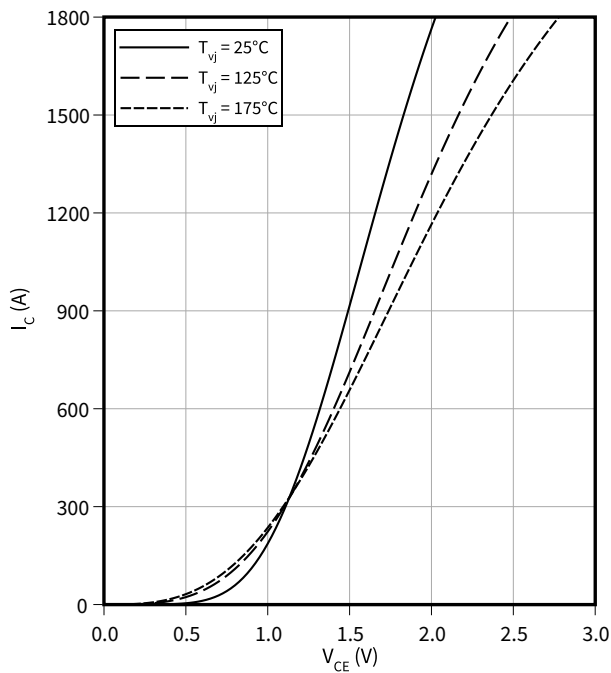
Note: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4

5 Characteristics diagrams

Output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

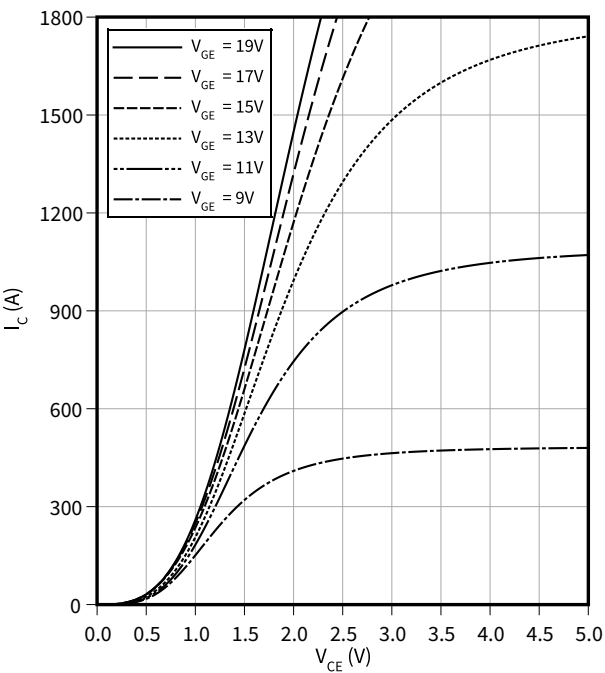
$V_{GE} = 15\text{ V}$



Output characteristic field (typical), IGBT, Inverter

$I_C = f(V_{CE})$

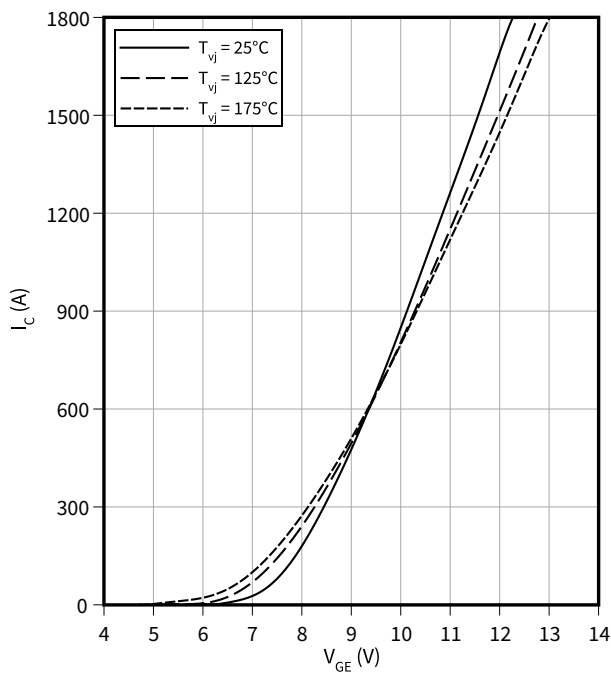
$T_{vj} = 175\text{ °C}$



Transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$

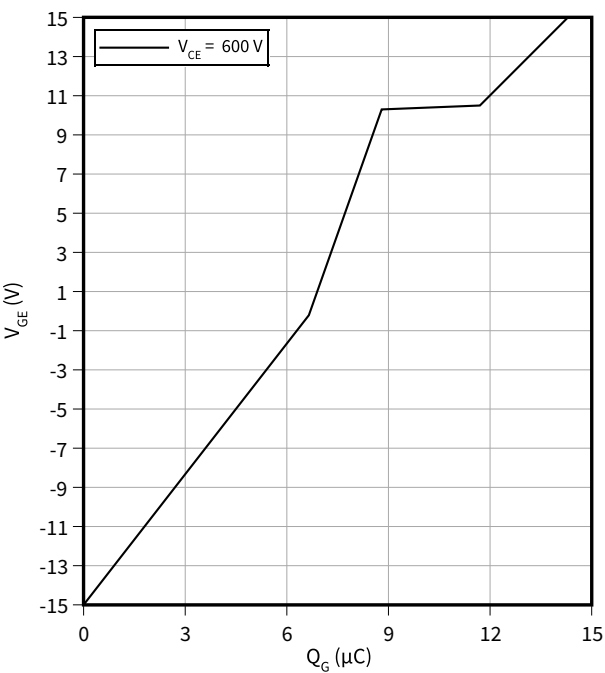
$V_{CE} = 20\text{ V}$



Gate charge characteristic (typical), IGBT, Inverter

$V_{GE} = f(Q_G)$

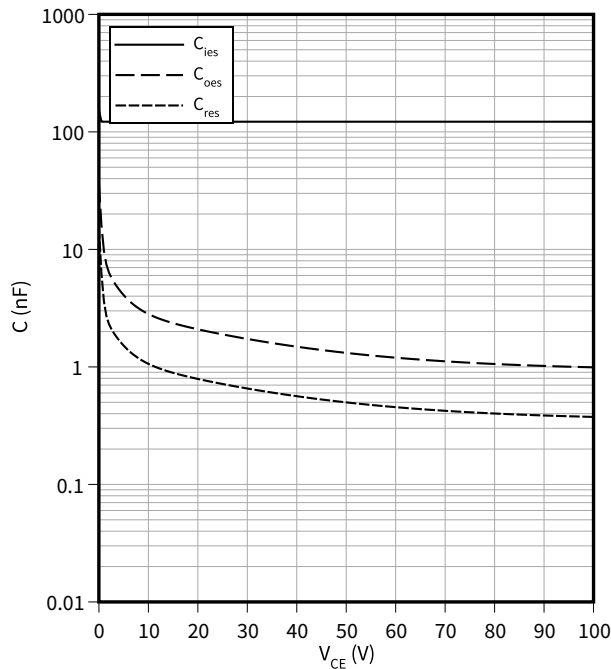
$T_{vj} = 25\text{ °C}, I_C = 900\text{ A}$



5 Characteristics diagrams

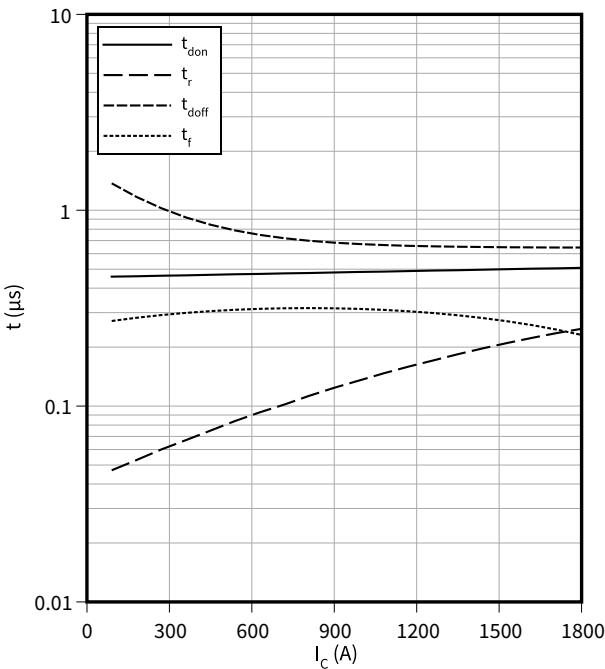
Capacity characteristic (typical), IGBT, Inverter

$C = f(V_{CE})$
 $f = 100\text{ kHz}$, $T_{vj} = 25\text{ °C}$, $V_{GE} = 0\text{ V}$



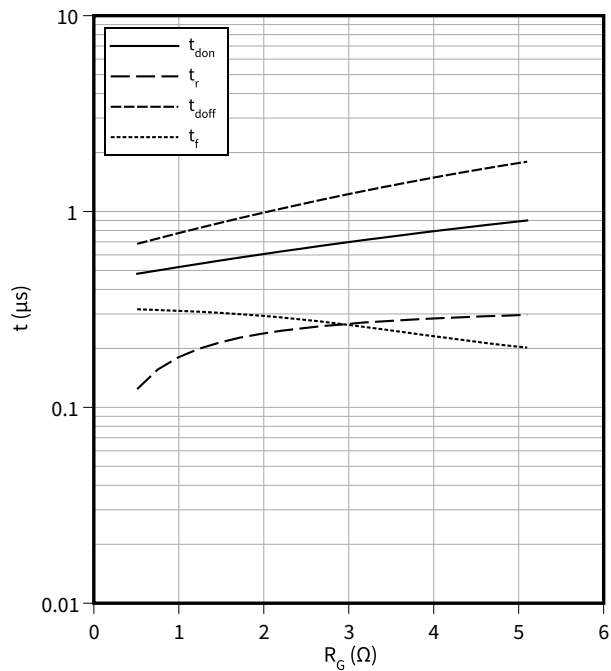
Switching times (typical), IGBT, Inverter

$t = f(I_C)$
 $R_{Goff} = 0.51\text{ }\Omega$, $R_{Gon} = 0.51\text{ }\Omega$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $T_{vj} = 175\text{ °C}$



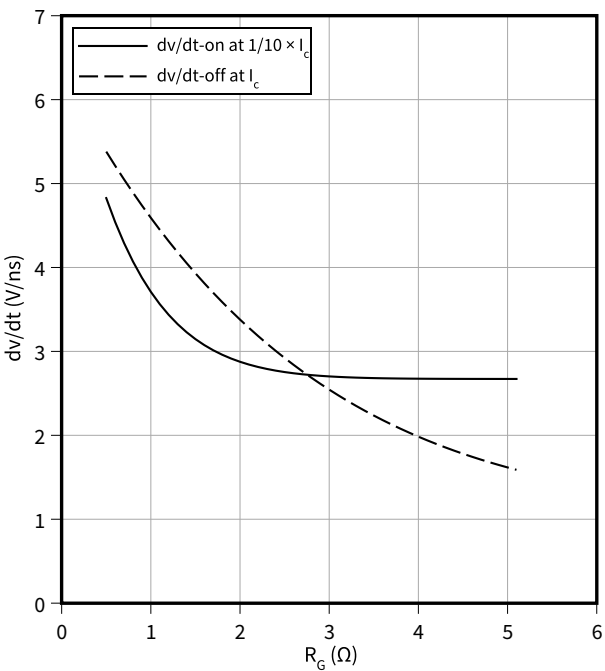
Switching times (typical), IGBT, Inverter

$t = f(R_G)$
 $I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $T_{vj} = 175\text{ °C}$



Voltage slope (typical), IGBT, Inverter

$dv/dt = f(R_G)$
 $I_C = 900\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $T_{vj} = 25\text{ °C}$

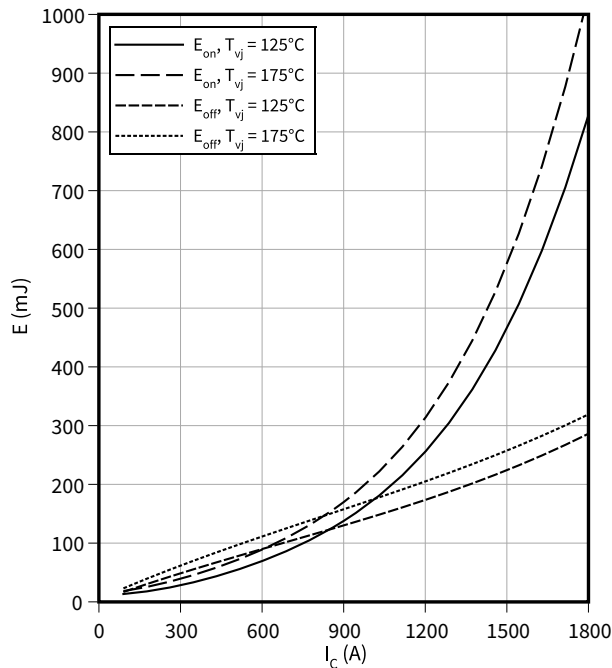


5 Characteristics diagrams

Switching losses (typical), IGBT, Inverter

$E = f(I_C)$

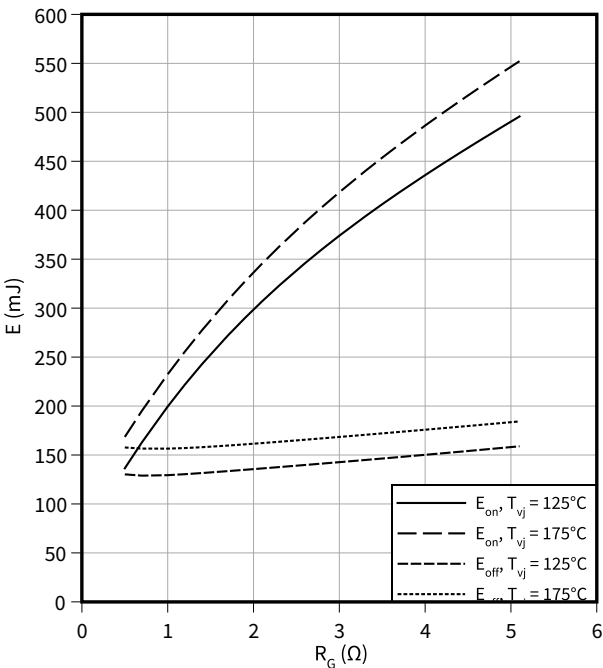
$V_{GE} = \pm 15\text{ V}$, $V_{CC} = 600\text{ V}$, $R_{Gon} = 0.51\ \Omega$, $R_{Goff} = 0.51\ \Omega$



Switching losses (typical), IGBT, Inverter

$E = f(R_G)$

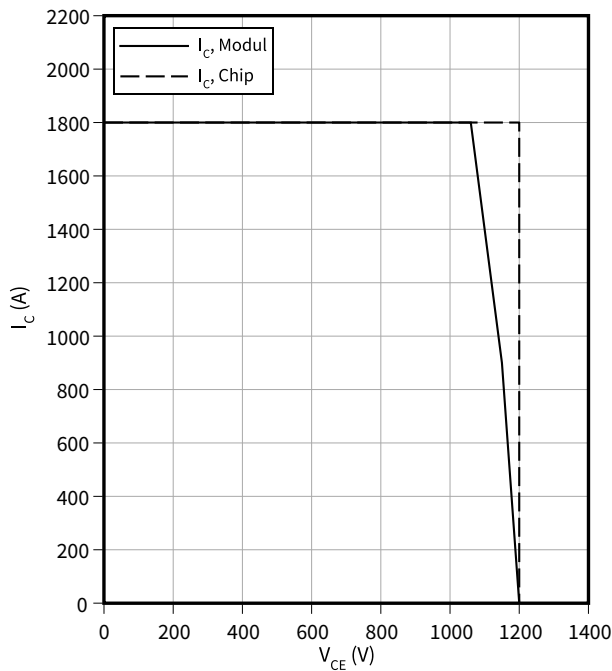
$I_C = 900\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $V_{CC} = 600\text{ V}$



Reverse bias safe operating area (RBSOA), IGBT, Inverter

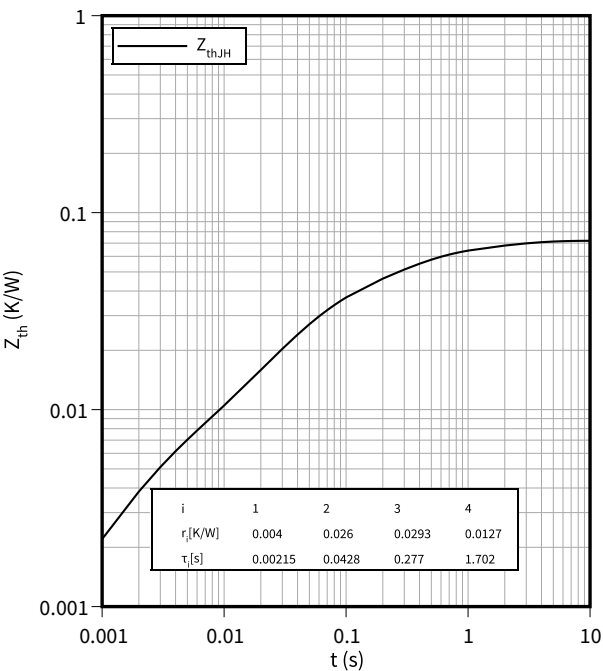
$I_C = f(V_{CE})$

$R_{Goff} = 0.51\ \Omega$, $V_{GE} = \pm 15\text{ V}$, $T_{vj} = 175\text{ °C}$



Transient thermal impedance, IGBT, Inverter

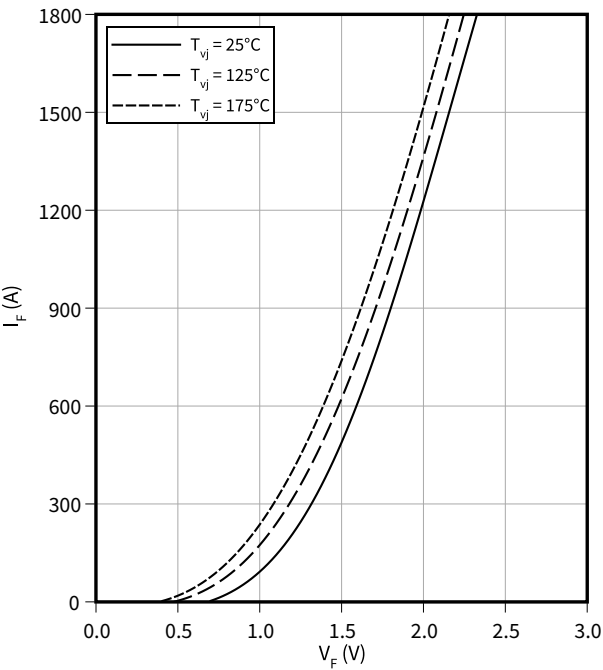
$Z_{th} = f(t)$



5 Characteristics diagrams

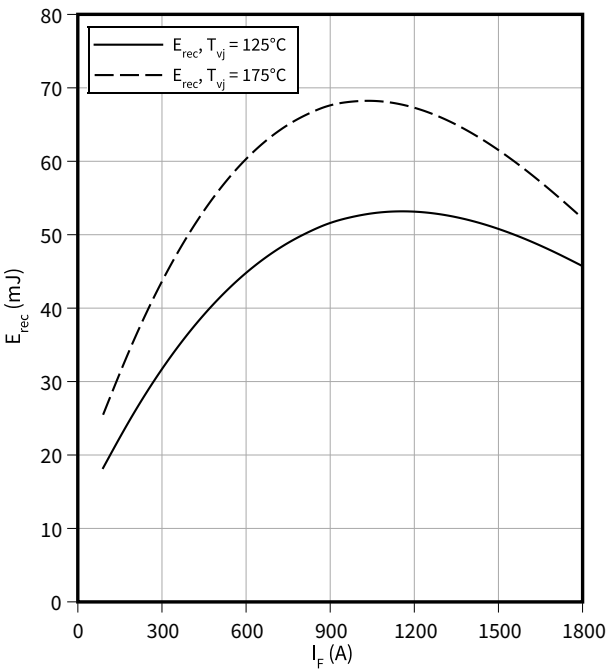
Forward characteristic (typical), Diode, Inverter

$I_F = f(V_F)$



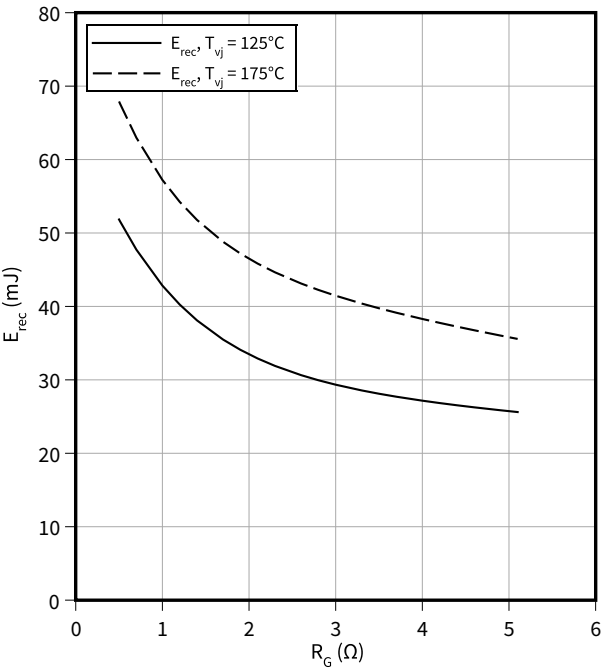
Switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$
 $R_{Gon} = R_{Gon}(IGBT)$, $V_{CC} = 600\text{ V}$



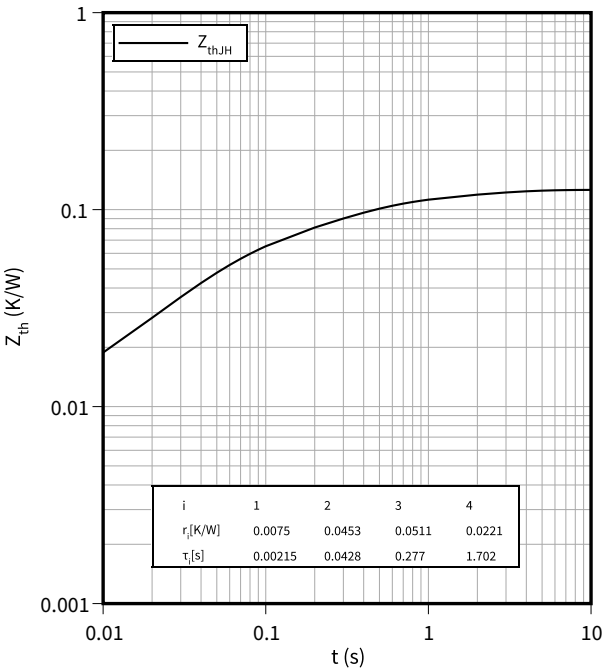
Switching losses (typical), Diode, Inverter

$E_{rec} = f(R_G)$
 $I_F = 900\text{ A}$, $V_{CC} = 600\text{ V}$



Transient thermal impedance, Diode, Inverter

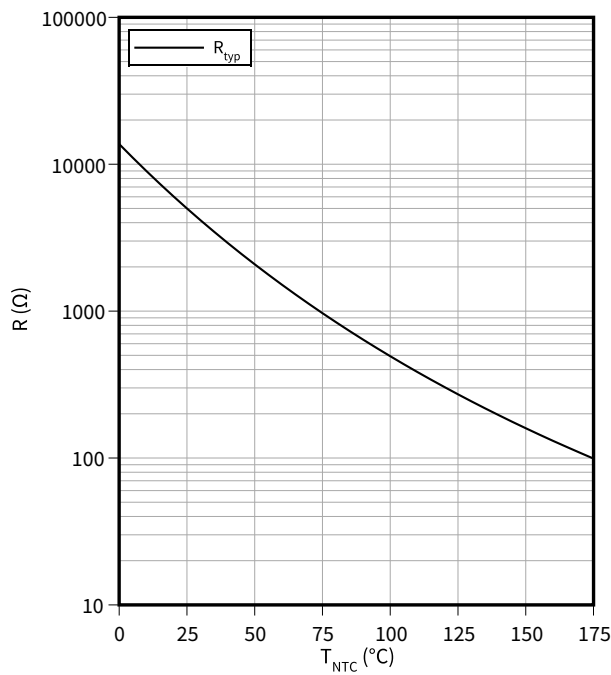
$Z_{th} = f(t)$



5 Characteristics diagrams

Temperature characteristic (typical), NTC-Thermistor

$R = f(T_{NTC})$



6 Circuit diagram

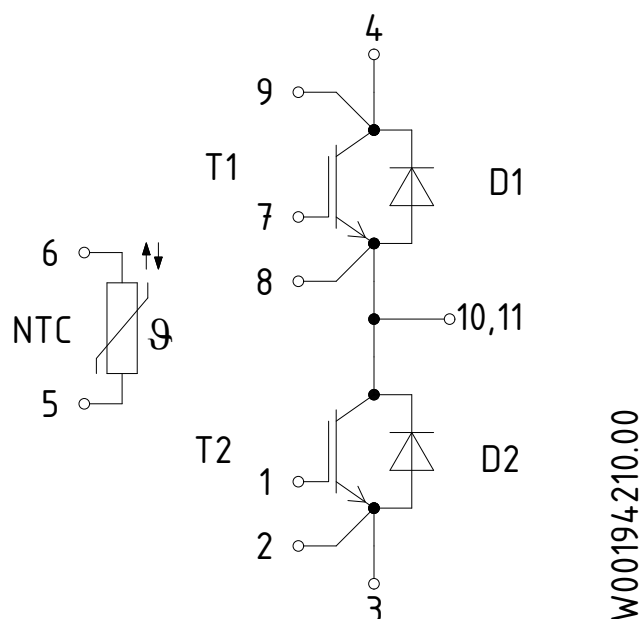


Figure 1

7 Package outlines

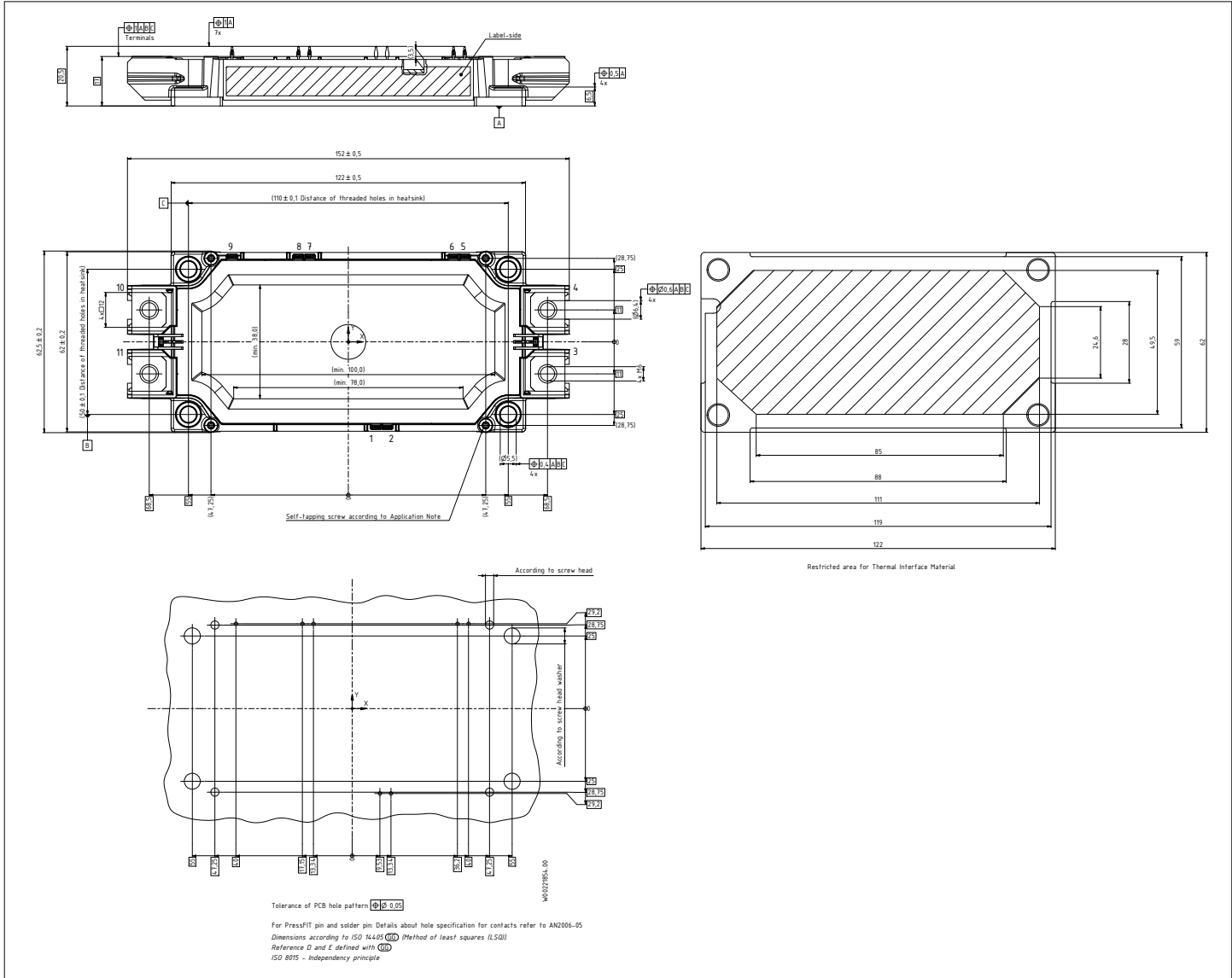


Figure 2

8 Module label code

Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	Content	Digit	Example
	Module serial number	1 – 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 – 21	15
	Date code (production week)	22 – 23	30
Example	 7154914284655054991153071549142846550549911530		

Figure 3

Revision history

Revision history

Document revision	Date of release	Description of changes
V2.0	2020-04-24	Preliminary datasheet
n/a	2020-09-01	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
0.20	2022-01-19	Preliminary datasheet
1.00	2024-03-06	Final datasheet

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